

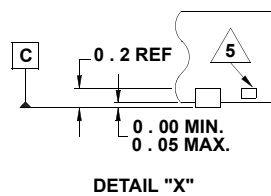
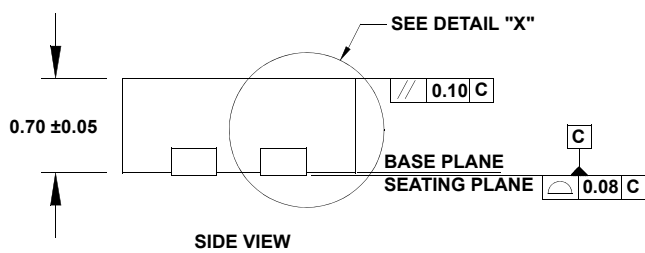
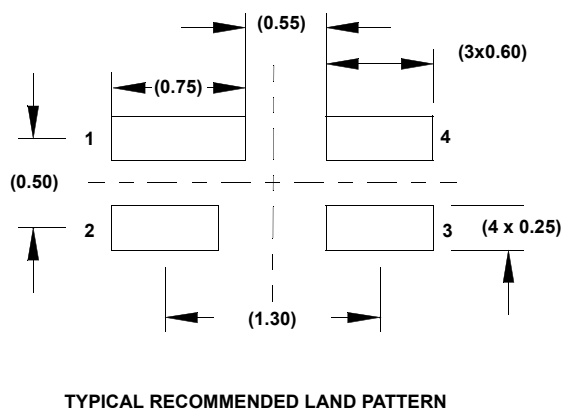
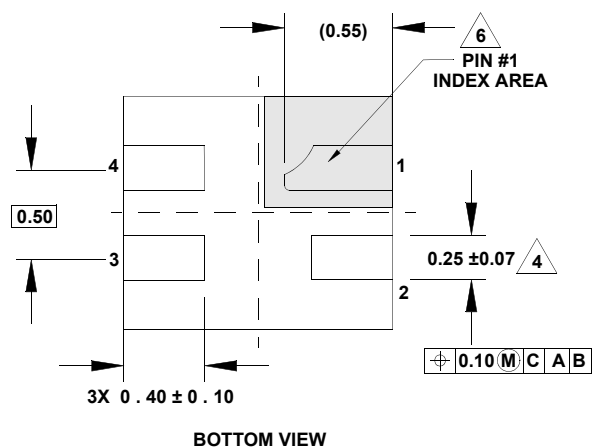
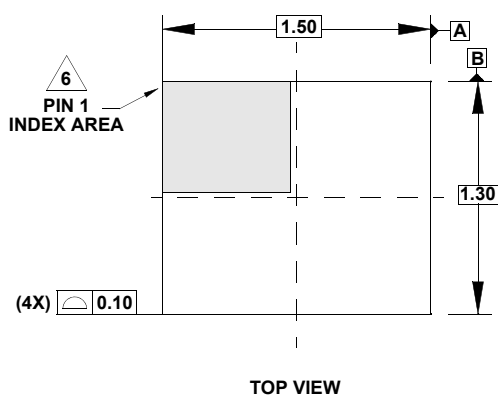
Plastic Packages for Integrated Circuits

Package Outline Drawing

L4.1.5x1.3

4 LD 1.5x1.3 OPTICAL DUAL FLAT NO-LEAD (ODFN)

Rev 6, 4/15



NOTES:

1. Dimensions are in millimeters.
Dimensions in () for Reference Only.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Dimension applies to the metallized terminal and is measured between 0.18mm and 0.32mm from the terminal tip.
5. Tiebar shown (if present) is a non-functional feature and may be located on any of the 4 sides (or ends).
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
7. This package not defined by JEDEC, but MO-229 can be used as a general reference.